



Upgrade of the vertex detector of the Belle II experiment

Jerome Baudot, for the VXD Upgrade R&D Working Group of the Belle II collaboration



- Context of the current VXD
- Opportunity for a VXD upgrade
- On-going relevant R&Ds
- Full simulations for optimisation

The VXD roles within the Belle II setup

■ Physics program @ SuperKEKB with Belle II

- Thorough test of Std Model
- Direct/indirect search for New Physics
- Hadronic Physics

} with billions of $B\bar{B}, c\bar{c}, \tau\bar{\tau}$ pairs
In "clean" environment of B-factory

⇒ The Belle II physics book
[PTEP 12 \(2019\) 123C01](#)

- Based on accumulation of 50 ab^{-1} of e^+e^- at $\sqrt{s} = M_{Y(4S)}$
- within ~10 years → instantaneous luminosity close to $10^{36} \text{ cm}^{-2}\cdot\text{cm}^{-1}$



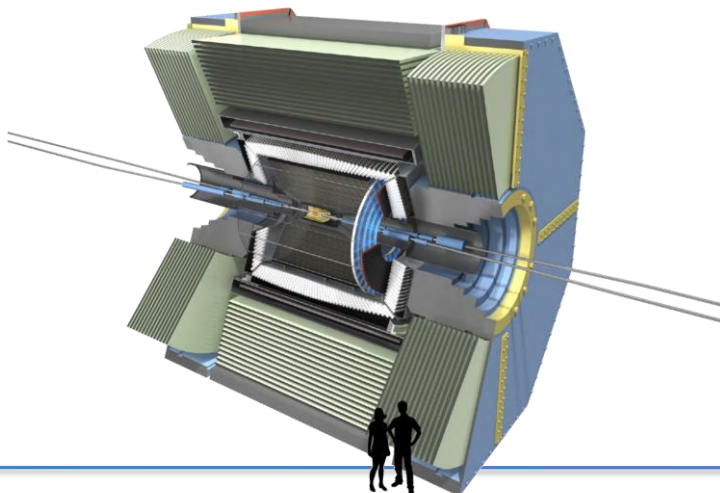
SuperKEKB collider implementing the nano-beam scheme @ high currents



High collision rate High beam-induced bkg

■ The Belle II experiment

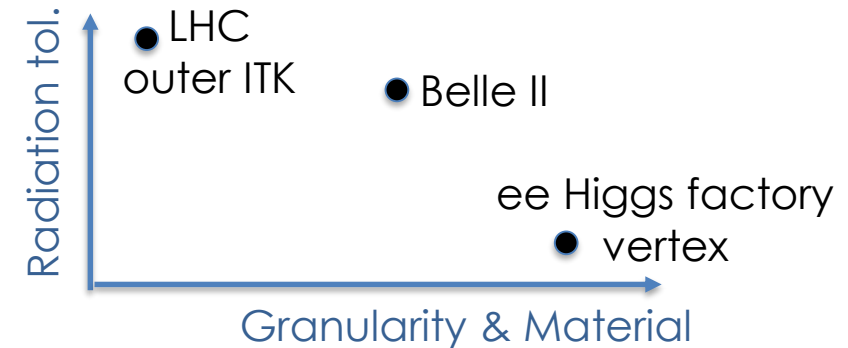
- "classical" B-factory detector + **enhanced features**



■ The vertex detector (VXD)

- Better vertexing ← lower boost
- Smarter tracking ← higher hit rate

- + Harsher radiation environment
- + Belle II trigger rate ~ 30 KHz

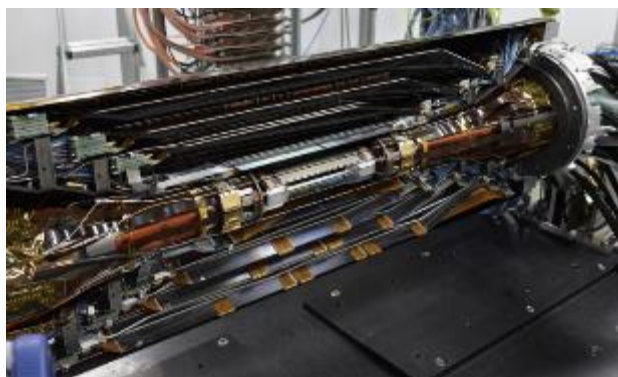


The current VXD

■ Two technology system

• **SVD = Double-Sided Strip Detector**

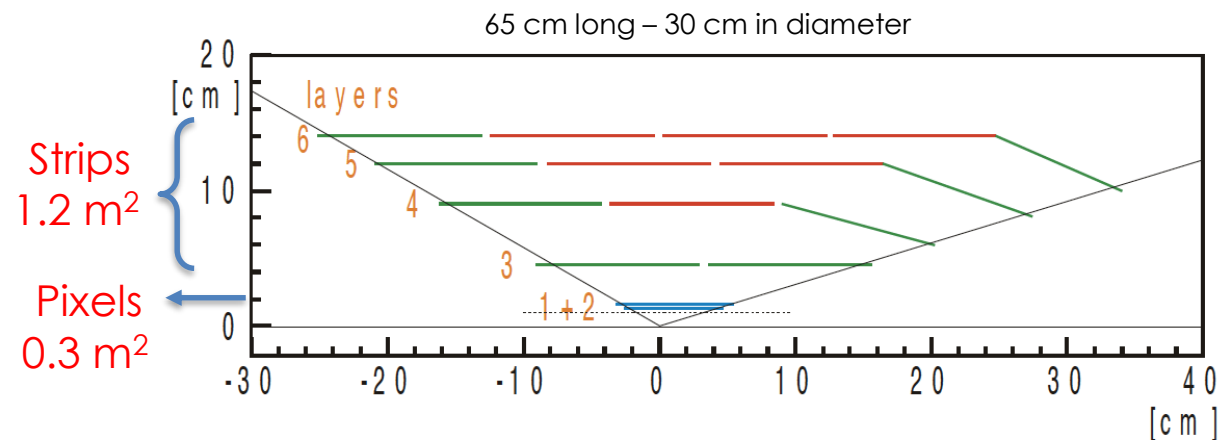
- Read-out sensor connected on sensor = Origami
- Hit time-stamping $\sigma_t \sim 2\text{-}3\text{ ns}$
- Spatial resolution $\sigma_{s.p.} \sim 20\text{ }\mu\text{m}$



• **PXD = DEPFET sensors**

- Very low material budget $0.2\% X_0$ / layer
- Small first layer radius = 1.4 cm
- Long integration time $20\text{ }\mu\text{s}$ / trigger rate & injection bkg

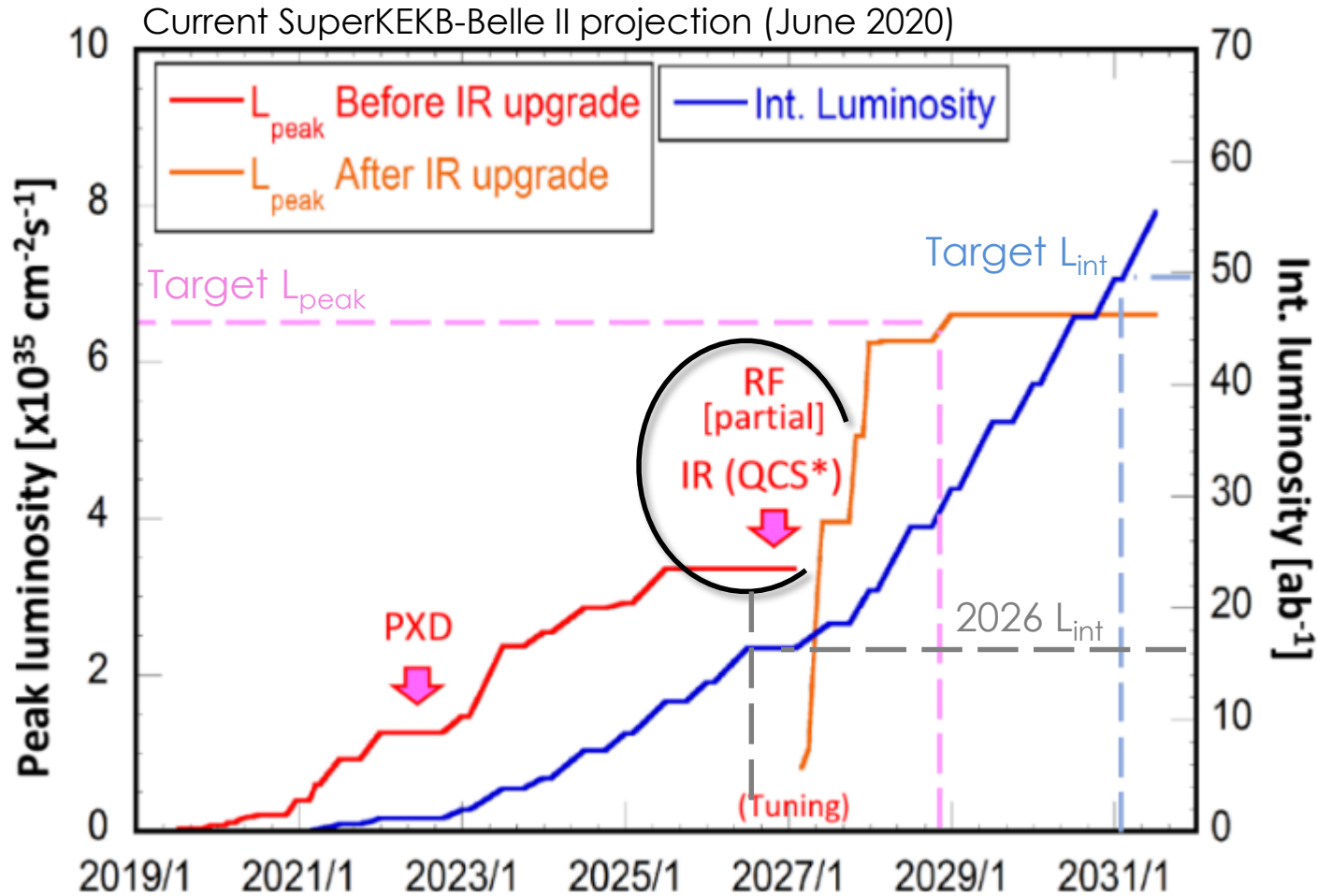
⇒ G.Rizzo [SVD overview](#) talk on Monday
+ Y.Uematsu [Hit-time reconstruction](#) poster
+ S.Hazra [Particle identification](#) Poster



⇒ Q.Liu [PXD overview](#) talk on Monday

The plan is successful so far! ⇒ C.Praz [Tracking performance and interaction point properties](#) talk on Tuesday

A decade of operation → Upgrades?



Short term ~ 2026

- Long shutdown for QCS upgrade
 - Needed before next jump in luminosity
 - Inner region needs to be opened up
 - Current VXD moved anyway
- ↓
- Opportunity for Belle II sub-det. upgrades
 - Let's investigate possibilities...
 - short time → with currently ~available techno.

Longer term > 2030

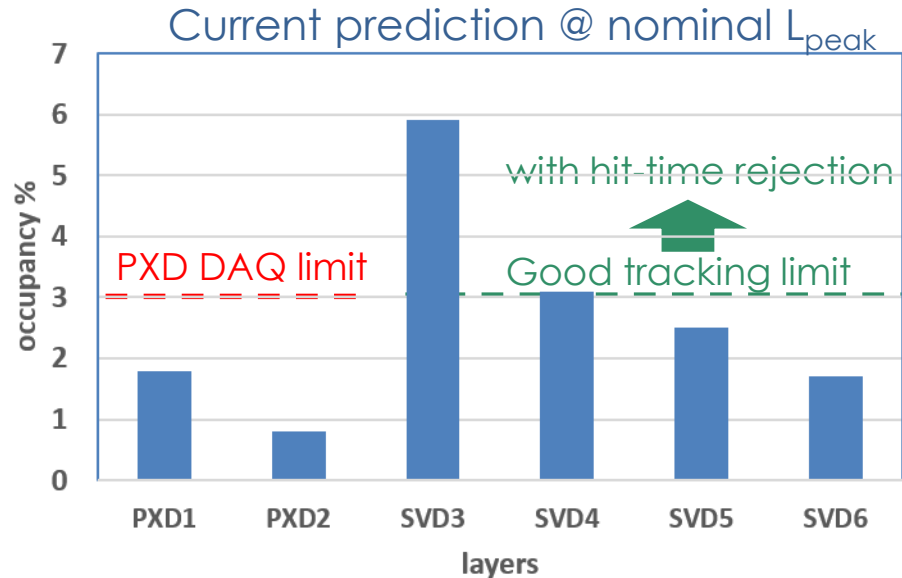
- Further increase of peak luminosity
 - Possibly beam polarization?
 - Enhanced physics program with 250 ab⁻¹
- ↓
- A renewed detector is needed
 - New set of requirements → not this talk!

Current VXD & nominal luminosity

⇒ [Belle II VXD Open workshop](#) July 2019

■ Beam-induced background extrapolations

- A long way to reach Data/MC ratio $\sim O(1)$

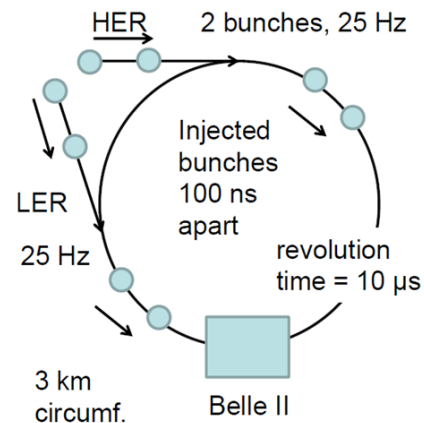


• **Still with large uncertainties**

- Drastic change of **beam optics** for max L_{peak}
 - β_y^* today 800 μm \rightarrow nominal 300 μm
- **Continuous injection** effect not predicted
 - currently too small for good estimate

■ Tracking / vertexing

- **Track pattern recognition with SVD hits only** required in // to tracking in Central Drift Chamber
- Then extrapolation to match PXD hits
 - Also used for reduction of PXD output bandwidth
- Final pointing resolution somewhat limited by beam-pipe thickness
 - 0.8 % X_0 \leftarrow partially required against synchrotron rad.



**Performances within limits
BUT without much margin**

Requirements for short-term VXD upgrade



■ Vertexing & Tracking performances at least as good as current VXD

- Radius range 14 – 135 mm
- Single point resolution $\leq 10\text{-}15 \mu\text{m}$
- Total material budget $< (2 \times 0.2 + 4 \times 0.7) \% X_0$
 - total power budget $< 1000 \text{ W}$

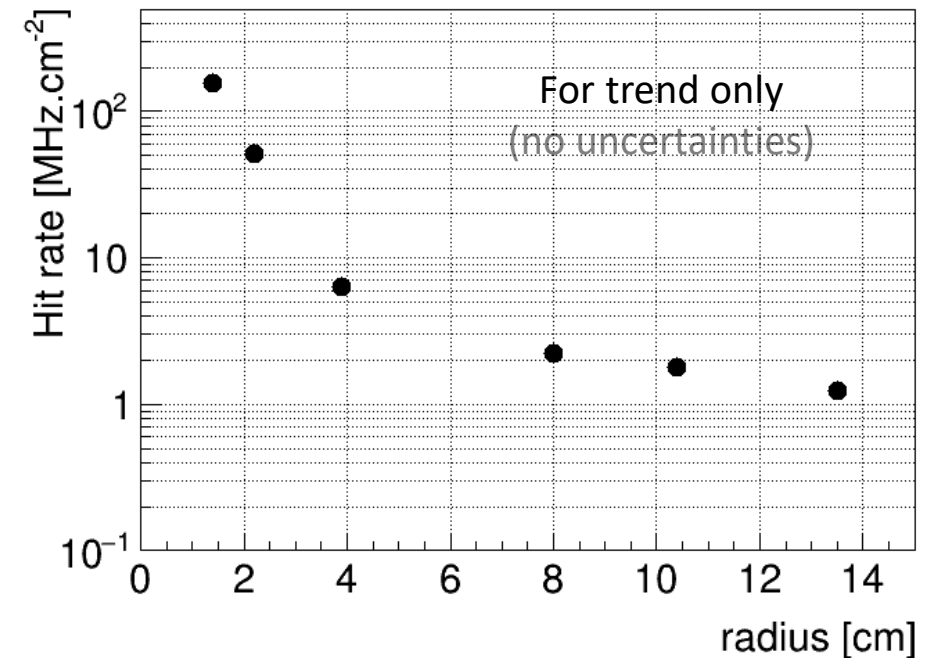
■ Robust against environment for inner layer ($r=1.4 \text{ cm}$)

- Hit-rate $\sim 120 \text{ MHz}\cdot\text{cm}^{-2}$
- Total Ionizing Dose $\sim 10 \text{ Mrad / year}$
- NIEL fluence $\sim 50 \times 10^{12} \text{ n}_{\text{eq}}\cdot\text{cm}^{-2} / \text{year}$

⚠ Based on current extrapolation with safety factor (x5)
bear in mind large uncertainties (previous slide)

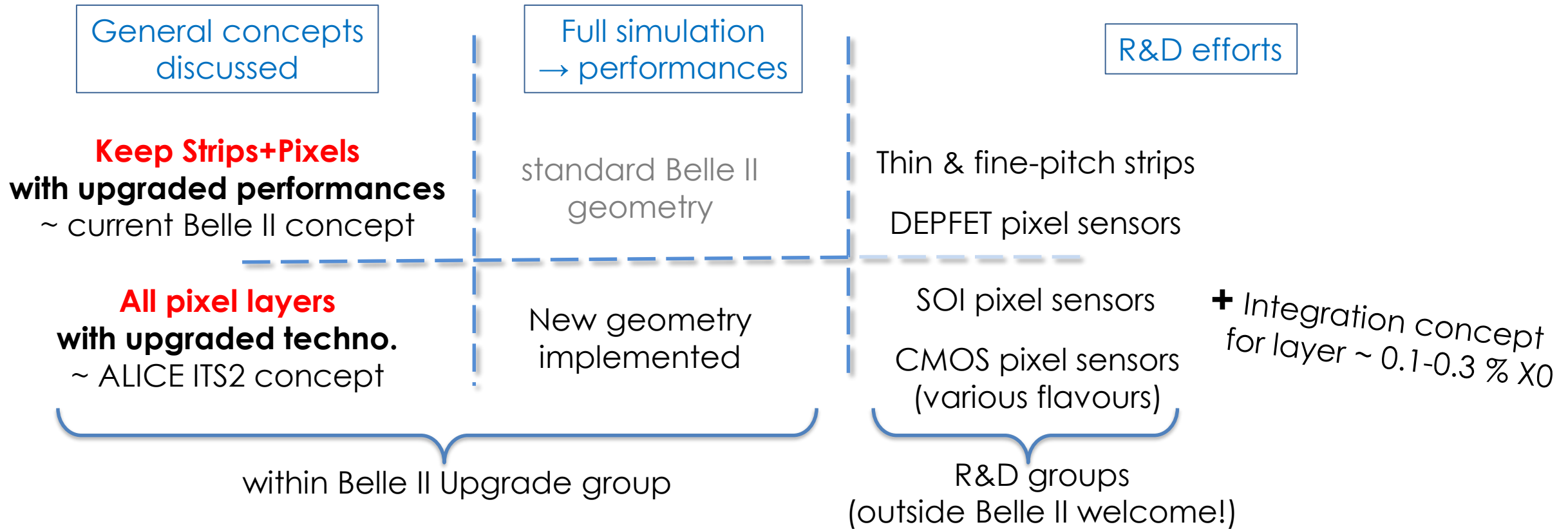
■ Possibly improve performances

- Impact parameter resolution
- Tracking efficiency ($p_T < 100 \text{ MeV}$) & Fake rate
- Faster High Level Trigger
 - Simplified track pattern recognition



- Timing if pixelated tracker ?
rough estimate $\rightarrow T_{\text{int}} \lesssim 100 \text{ ns}$

Current strategy



Effort built up to answer within ~1 year

- Which concepts bring best performances?
- Which technology fit requirements?
- Which technology can allow install in ~2026?

➔ CDR

Thin and fine-pitch DSSD

@ KEK



■ Main R&D targets

- Handling higher hit-rate / SVD
 - 10 MHz/cm² (radii>3 cm)
- Improved resolution σ_z & decrease material budget
- Longer trigger latency & rate



■ R&D paths

- Shorter strips
- Finer pitch
- Thinner sensor

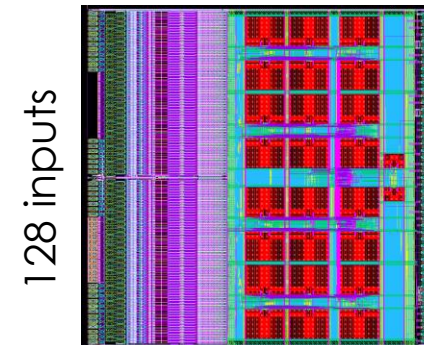


■ R&D challenges

- Heat dissipation (larger #chan.)
- Noise reduction (lower signal)

■ Solutions

- **Double-Sided Sensors** prototyped by Micron
- **Front-End ASIC = SNAP128A** under dvpmt
 - Based on SiT chip for g-2 (J-PARC experiment)
 - 180 nm CMOS process



- ENC = 650 e⁻
- Total power 2.8 mW/chan.
- 127 MHz output
- $\sigma_t \sim 8$ ns
- 2k-depth memory
→ latency ~ 16 μ s

Current

Sensor dim.	Thickness	Pitch P-side	Pitch N-side
40x125 mm ² 60x125 mm ²	300-320 μ m	50-75 μ m	160-240 μ m



(with intermediate strip)

Upgrade

51.2x57.6 mm ²	140 μ m	50 μ m	75 μ m
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⇒ K.Nakamura [Development of thin and fine-pitch DSSD](#) poster

⇒ First Sensor+FEE in 2021

DEPFET pixel sensors



Belle II DEPFET collaboration

Current Belle II - PXD

- First use of the technology in HEP experiment
- Many lessons learned

R&D directions

- **Gain increase** with shorter FET length L
 - thinner oxide
 - higher signal → improved rad. tolerance

$$g = \frac{dI_{\text{drain}}}{dQ} \propto \sqrt{\frac{t_{\text{ox}}}{L^3}}$$

- Rotating read-out direction + switcher intergration

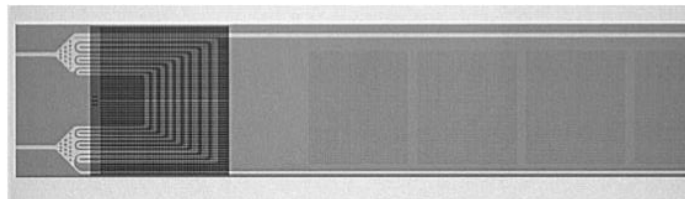
- Speed x3
- Pixel size along beam x1/2

- Faster driving & read-out circuits

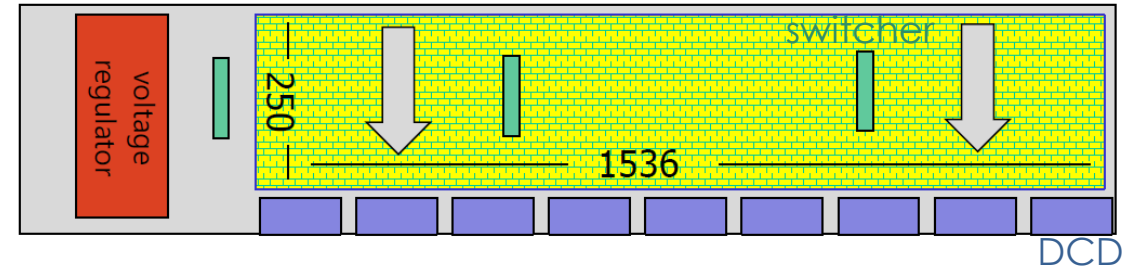
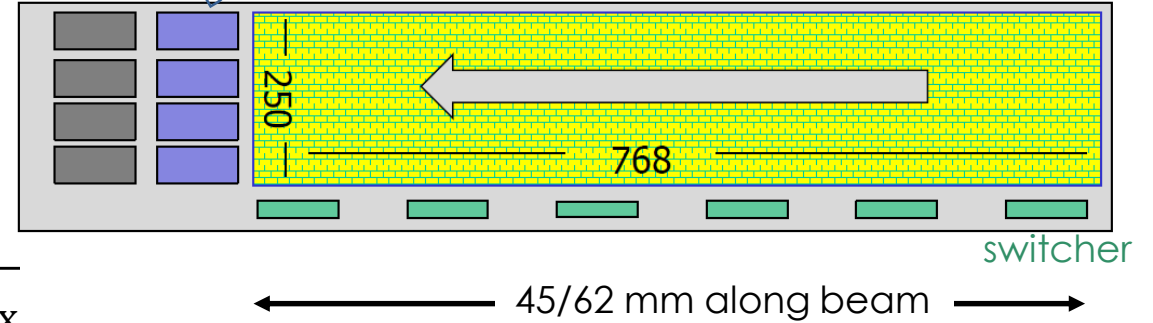
- Require advanced processed
- Speed x2

- **All-silicon module** improvements

- Microchannel cooling
- Thinner drivers



Data handler
Drain Current Digitizer
DCD



Within reach

- T_{int} : 20 \supset 3 μs
- Improved σ_z
- Mat. budget 0.21 \supset 0.15 % X_0

DuTiP - SOI pixel sensors

@ KEK

■ Main R&D targets

- **Low material budget**
 - Monolithic technology
- **Handling high-rate**
 - Time-stamping < 100 ns
 - Global-shutter style



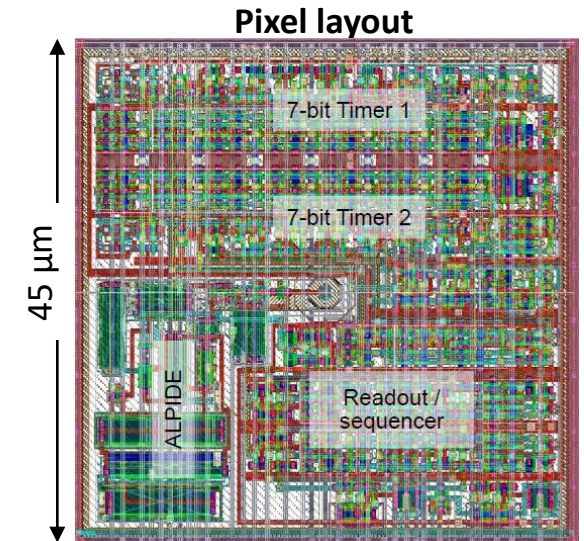
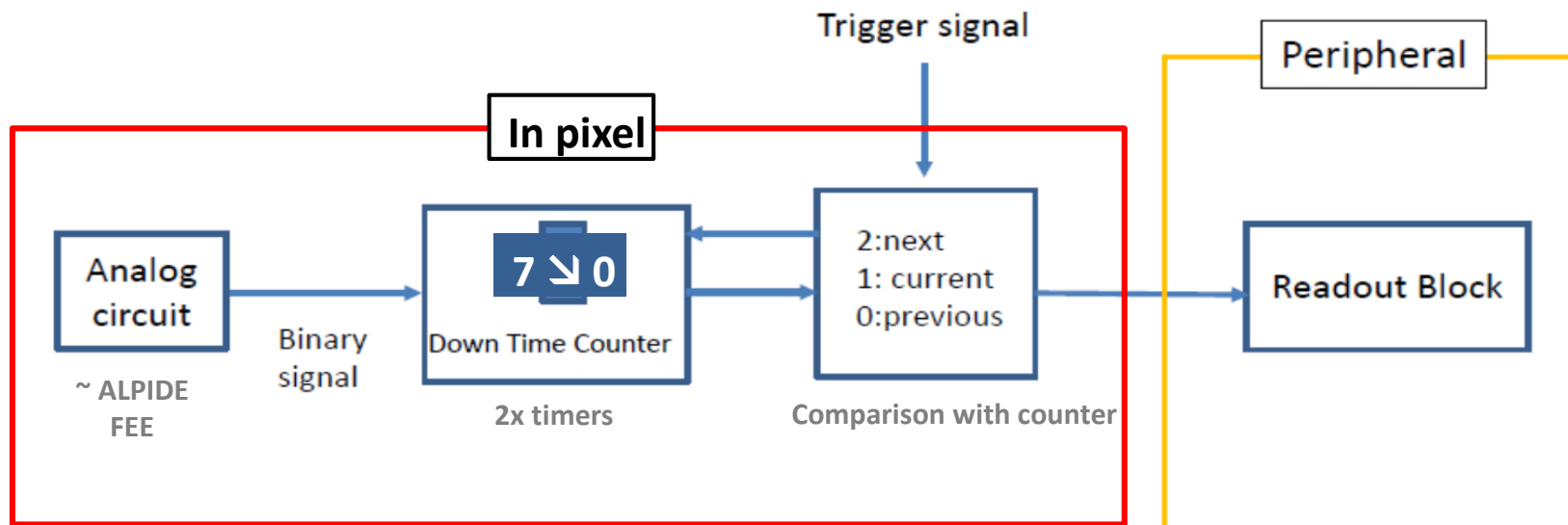
■ Dual Timer Pixel concept

- 16 MHz clock for **TIMER**
- 2x 60 ns “integration” window
- Trigger latency 8 μ s
- Occupancy \ll 0.1 %



■ SOI Implementation

- 0.2 μ m LAPIS
- Full depletion
- Pixel pitch 45x45 μ m²
- Sensitive thickness 50-75 μ m



⇒ Initial prototype DuTiP 1 submission in Nov.2020

⇒ M.Yamada [R&D status of monolithic SOI pixel sensor for vertex detector](#) talk on Wed.

CMOS pixel sensor options



⇒ Various R&D on-going outside Belle II

⇒ [Monolithic sessions](#) on Wednesday

Sensor available 2020	MIMOSIS-1 (CBM-MVD)	Belle II requirements "First guess"	MONOPIX-2 (ATLAS-ITK)	ATLASPix3 (ATLAS-ITK)
Time precision (ns)	5000	50 to 100	25	25
Pixel pitch (μm^2)	30x27	30x30 to 40x40	33x33	150x50
TID (Mrad)	5	10	100	100
Power (mW/cm ²)	~50	< 100 to 200	~150	?
Trigger delay (μs)	No trigger	5 → 10	long	long

In test
IPHC

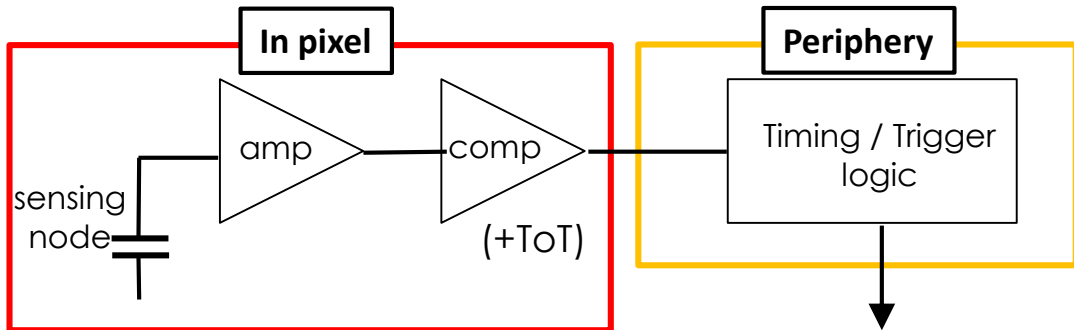
Submitted
Bonn, CERN, CPPM

Tested
Barcelona, CPPM, Geneva,
Heidelberg, KIT, Liverpool

180 nm HR-CMOS process

~full depletion

180 nm HV-CMOS process



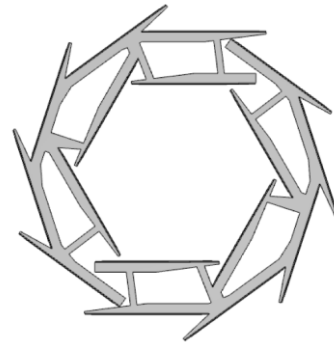
- Demonstrated
 - Monolithic & low power → low material budget granted
 - Excellent granularity → $\sigma_{s.p.} \sim 5-10 \mu\text{m}$
 - Short integration → occupancy = $O(10^{-3})$
- ⇒ 1st dedicated version in 2021 ~ realistic

Integration concept

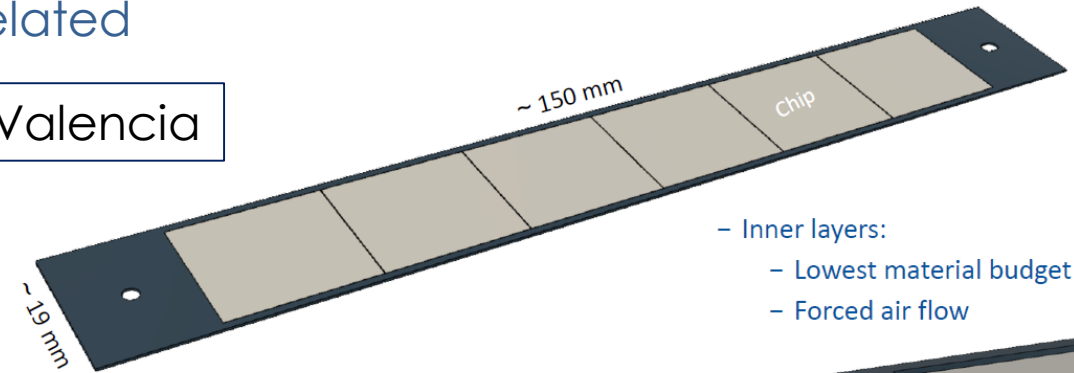
Context = new geometry with all VXD fully pixelated

■ Inner layers = full silicon module

- 2 to 3 layers, radius < 4 cm
- Target 0.1 % X_0 / layer



@ IFIC, Valencia



- Inner layers:
 - Lowest material budget
 - Forced air flow

Single piece of silicon
6 sensors per ladder
100 μ m gap between sensors



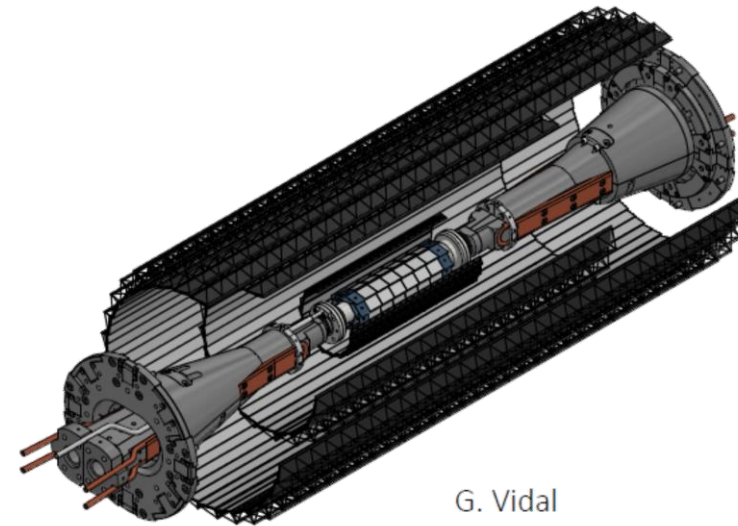
C.Marinias
G.Vidal

■ Outer layers ~ ALICE-ITS concept

- 3 to 4 layers, radius 4-14 cm
- Target 0.3 % X_0 / layer



C.Gargiulo
CERN - ALICE



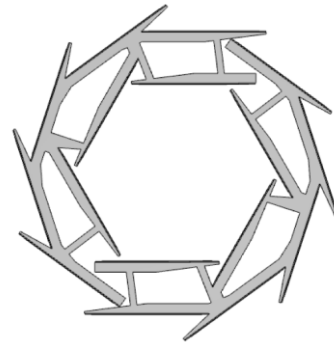
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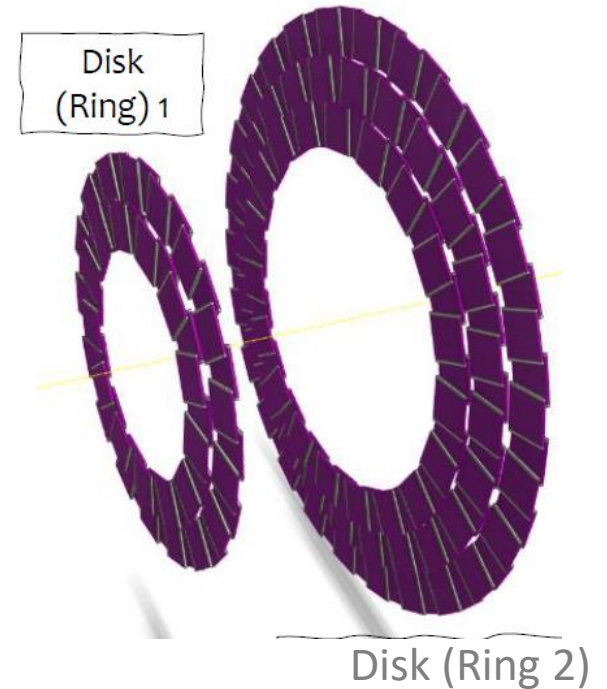


■ Forward disks

- 2 disks at $z = 16.5$ & 25.6 cm
- Target 0.3 % X_0 / layer

@ INFN-Pisa

F.Bosi
M.Massa

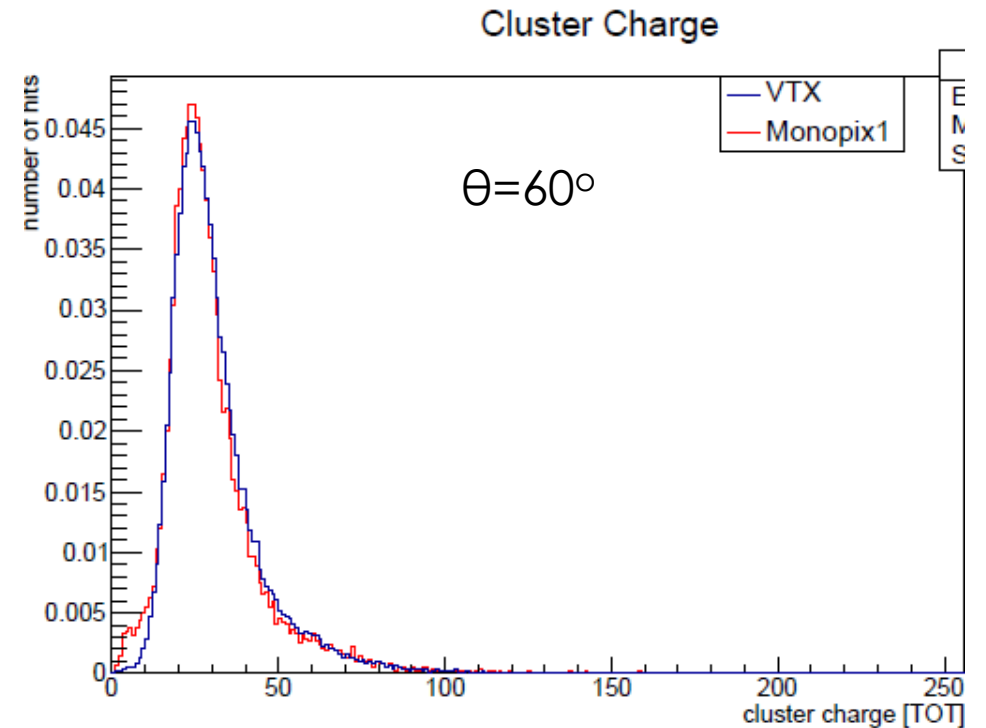
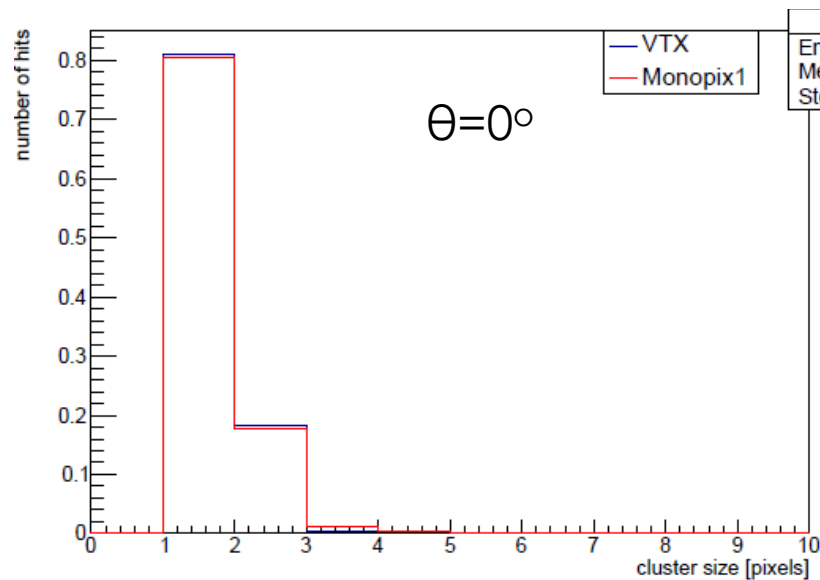


Simulated tracking performances

Context = new geometry with all VXD fully pixelated = VTX

Realistic pixel sensor model

- Digitizer assuming
 - fully depleted thin layer 30 μm
 - Pixel 33x33 μm^2 with 7bits Time over Threshold
- Tuned with Monopix-1 beam data**
 - JINST 14 (2019) C06006
 - Pitch 40x40 μm^2
 - ToT 6 bits

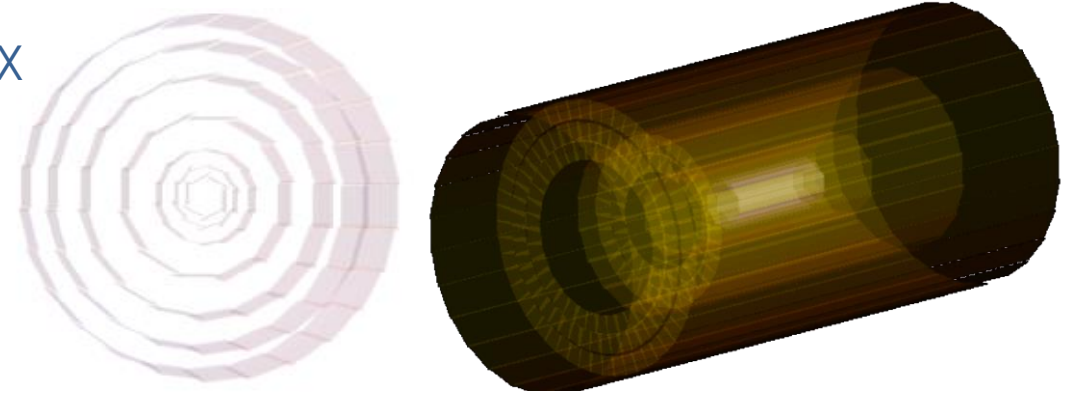


Monopix-1 data from **Bonn group**
Test-beam at DESY with 5 GeV e-

Results by T.Fillinger (Strasbourg), B.Schwenker (Göttingen), C.Wessel (Bonn)

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Realistic pixel sensor model

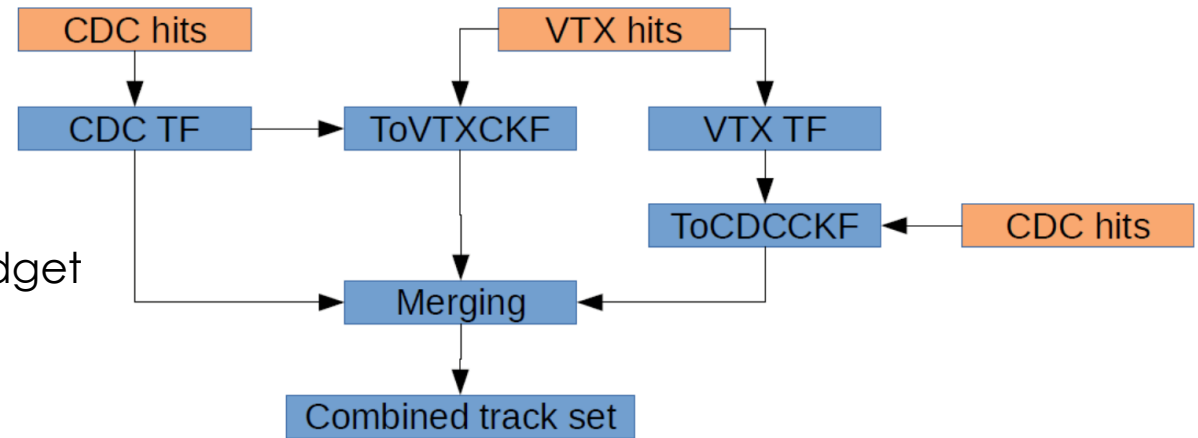
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Geometry

- Taken from fast simulation
- 5 or 7 barrel layers with/without 2 forward disks
- Crude layer description but with targeted material budget
 - per layer: 0.1 % X_0 for radii <4 cm then 0.3 % X_0

Full tracking chain

- VTX standalone
 - CDC standalone
- } then combined



All VTX layers included in pattern-reco. → other possible simpler/faster scheme ⇒ beneficial to High Level Trigger

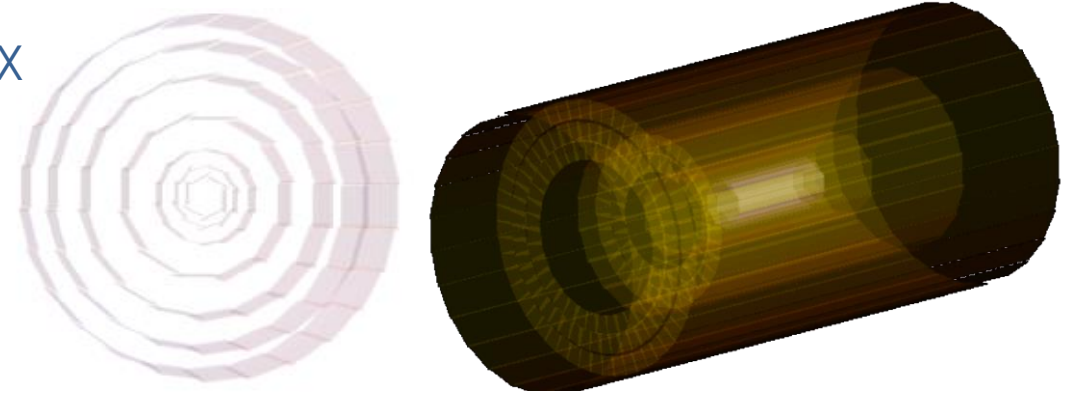
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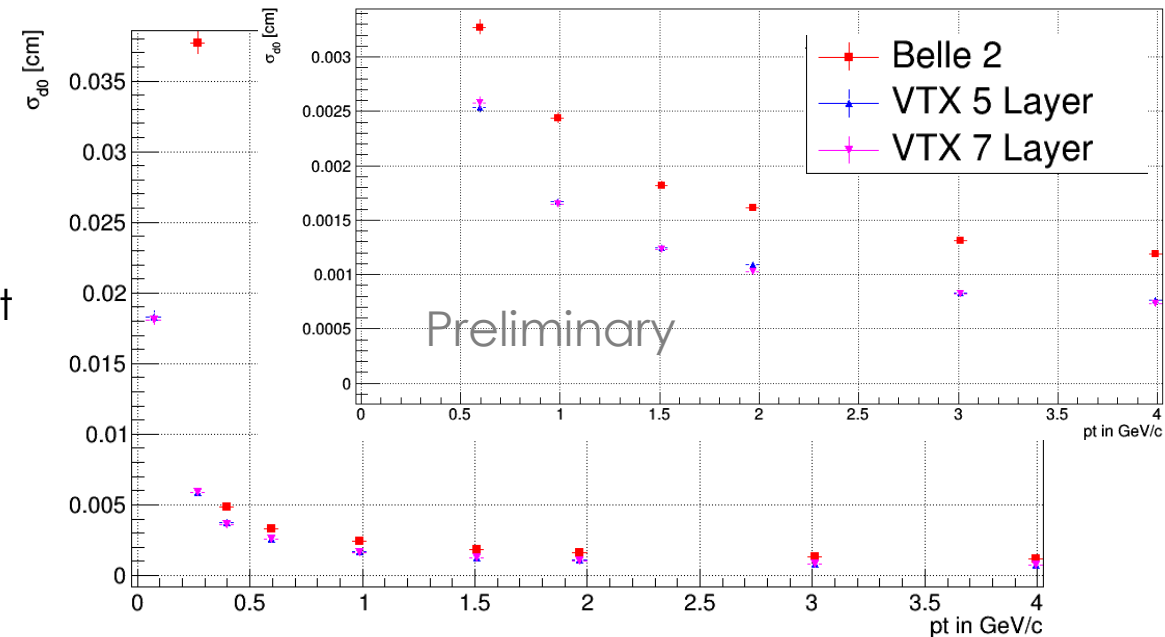


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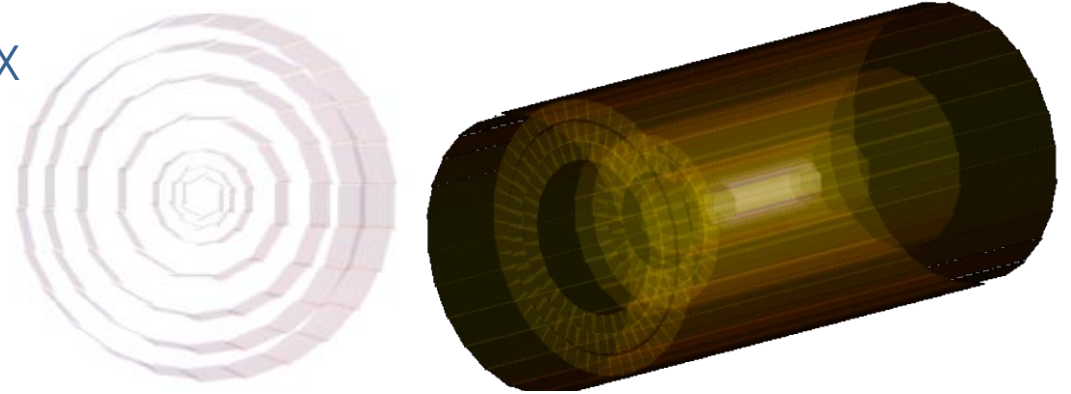
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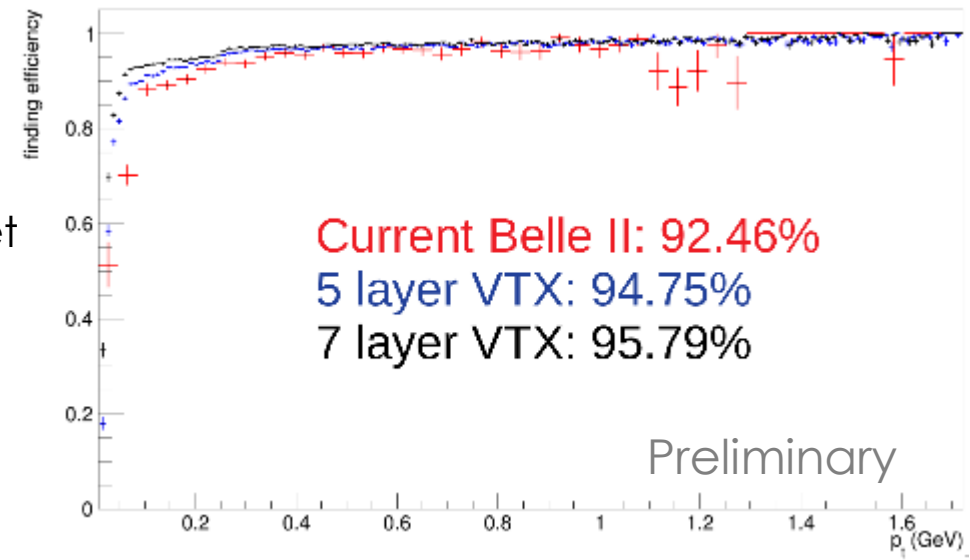


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Summary & Outlook

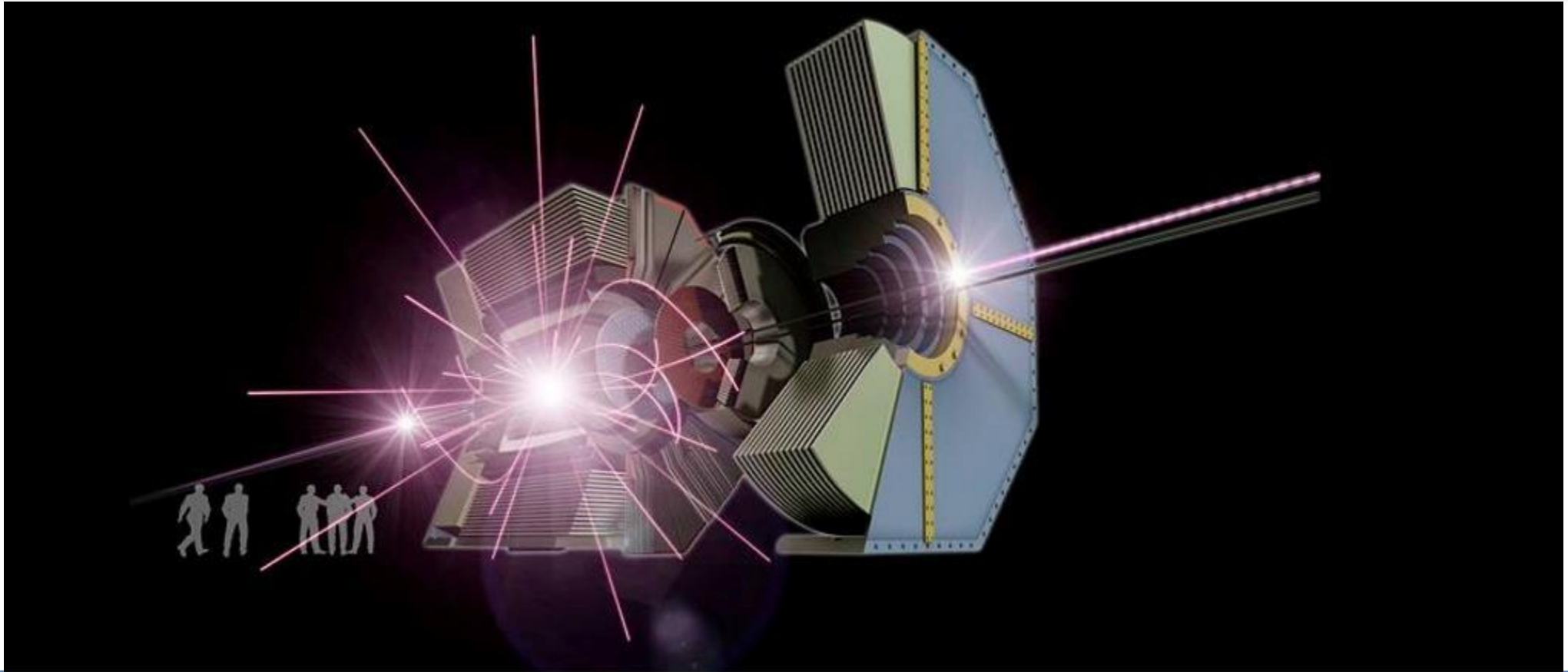


- There is an opportunity for an upgraded vertex detector (VXD) in Belle II
 - Short-term target ~ 2026
 - Main requirement = additional robustness / hit-rate & radiation environment
 - Also opportunity to enhance vertexing & tracking performances

⇒ Will benefit to physics with $> 30 \text{ ab}^{-1}$ still to accumulate over expected 50 ab^{-1}
- Initial work status
 - R&D concepts on various strip / pixel & integration technologies on-going
 - **Full simulation for fully pixelated VXD option** → first evaluation of expected performances
- Still a lot to do in a short time
 - Letters of Intent describing draft proposals @ end of 2020
 - First dedicated prototypes in 2021 → CDR 2021
 - **Physics benchmarking with full simulation**
 - Then 5 years rush to development & install

⇒ It is time to join,
R&D contributors outside
Belle II welcomed!

SUPPLEMENTARY SLIDES



■ Belle II related talk

• **PXD**

- Q.Liu [Operational Experience and Performance of the Belle II Pixel Detector](#) Talk on Monday 5th

• **SVD**

- G.Rizzo [The Belle II SVD performance and operational experience in the first data taking](#) Talk on Monday 5th
- Y.Uematsu [A Study for Hit-time Reconstruction of Belle II Silicon Vertex Detector](#) Poster on Monday 5th
- S.Hazra [Particle identification in Belle II silicon vertex detector](#) Poster on Monday 5th

• **Tracking**

- C.Praz [Tracking performance and interaction point properties at the Belle II experiment](#) Talk on Tuesday 6th

• **R&D**

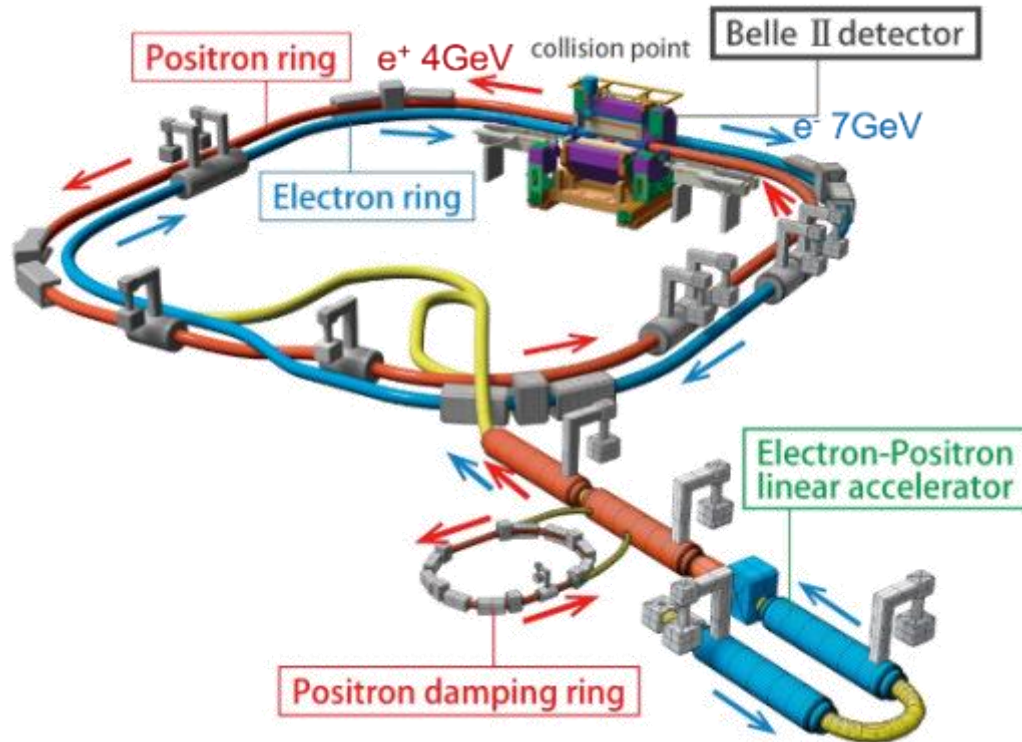
- K.Nakamura [Development of the thin and fine-pitch silicon strip detector aiming for the Belle II upgrade](#) Poster on Monday 5th

■ Generic R&D on pixel

• Sessions on Wednesday 7th morning: [Monolithic I](#) [Monolithic II](#)

- M.Yamada [R&D status of monolithic SOI pixel sensor for vertex detector Wednesday](#) talk
- M.Barbero [Depleted Monolithic Active Pixel Sensors in LFoundry 150 nm and TowerJazz 180 nm CMOS technologies: The Monopix developments](#) talk
- H-C.Augustin [MuPix10: First Results from the Final Design](#) talk

SuperKEKB collider

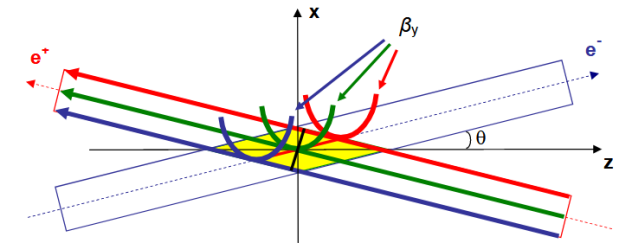


Recipe to high luminosity

Lorentz factor γ_{\pm}
 beam current I_{\pm}
 beam-beam parameter $\xi_{y\pm}$ \rightarrow High currents: $> 1A$
 geometrical reduction factors $\left(\frac{R_L}{R_{\xi}}\right)$
 beam aspect ratio at the IP $\left(\frac{\sigma_y^*}{\sigma_x^*}\right)$
 vertical beta-function at the IP $\beta_{y\pm}^*$
 \rightarrow Nano-scale beam size: $\sigma_x \times \sigma_y \sim 10\mu\text{m} \times 60\text{ nm}$
 $\beta_y^* \ll 1\text{ mm}$

$$L = \frac{\gamma_{\pm}}{2er_e} \left(1 + \frac{\sigma_y^*}{\sigma_x^*}\right) \frac{I_{\pm} \xi_{y\pm}}{\beta_{y\pm}^*} \left(\frac{R_L}{R_{\xi}}\right)$$

& specific beam crossing features
 Crossing angle (83 mrad) + crab waist (80%)



Cost = severe beam induced background

	KEKB	SuperKEKB	
		2020	Nominal
Energy (GeV) LER/HER	3.5 / 8	4 / 7	
Current (A) LER/HER	1.6/1.2	0.7/0.6	2.8 / 2.0
β_y^* (mm)	5.9	0.8	0.3
Instant. Lumi. ($\text{cm}^{-2} \cdot \text{s}^{-1}$)	2.1×10^{34}	2.4×10^{34}	$\sim 6 \times 10^{35}$

Belle II detector



■ Planned for better performances / Belle under:

- Higher beam-background rate
- Higher trigger rate (30 kHz)

EM Calorimeter (CDC) *upgraded*
CsI(Tl), waveform sampling (barrel+ endcap)

Final focusing magnets *new*

Beryllium beam pipe
2cm diameter *new*

SuperCond. Solenoid
1.5 T magnetic field

Vertex Detector (VXD = PXD+SVD) *new*
2 layers DEPFET pixels + 4 layers DSSD

KLong and muon detector (KLM) *upgraded*
Resistive Plate Chambers (barrel outer layers)
Scintillator + WLSF + SiPM's (end-caps , inner 2 barrel layers)

Particle Identification
TOP detector system (barrel)
Prox. focusing Aerogel RICH (fwd) *new*

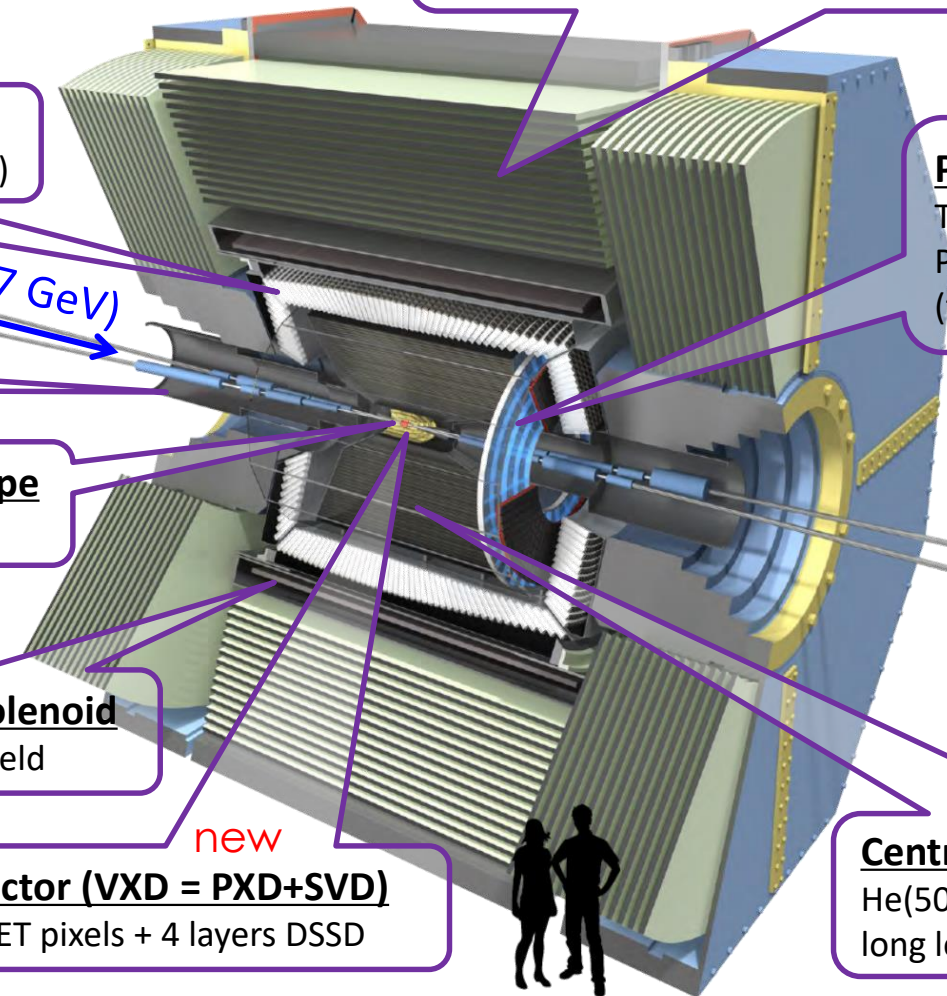
Central Drift Chamber *new*
He(50%):C₂H₆(50%), small cells,
long lever arm, fast electronics

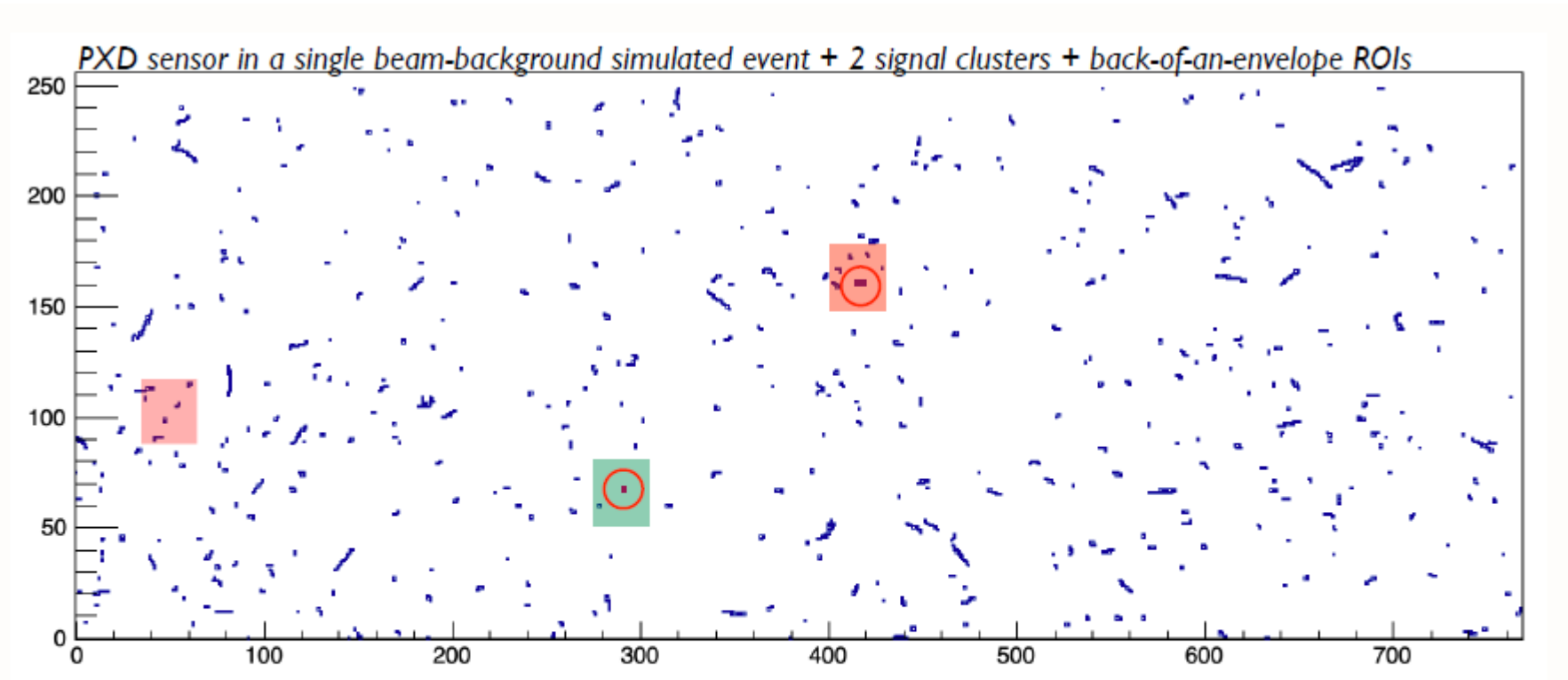
electrons (7 GeV)

positrons (4 GeV)



Belle II collab
~1000 researches / 26 countries





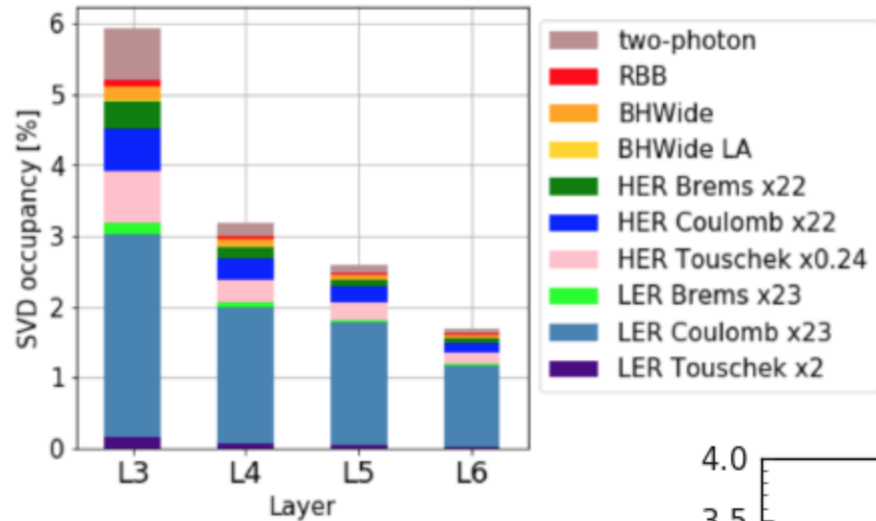
- ◆ A PXD sensor frame + the ROIs from the HLT + nominal expected background

From Eugenio Paoloni, July 2019

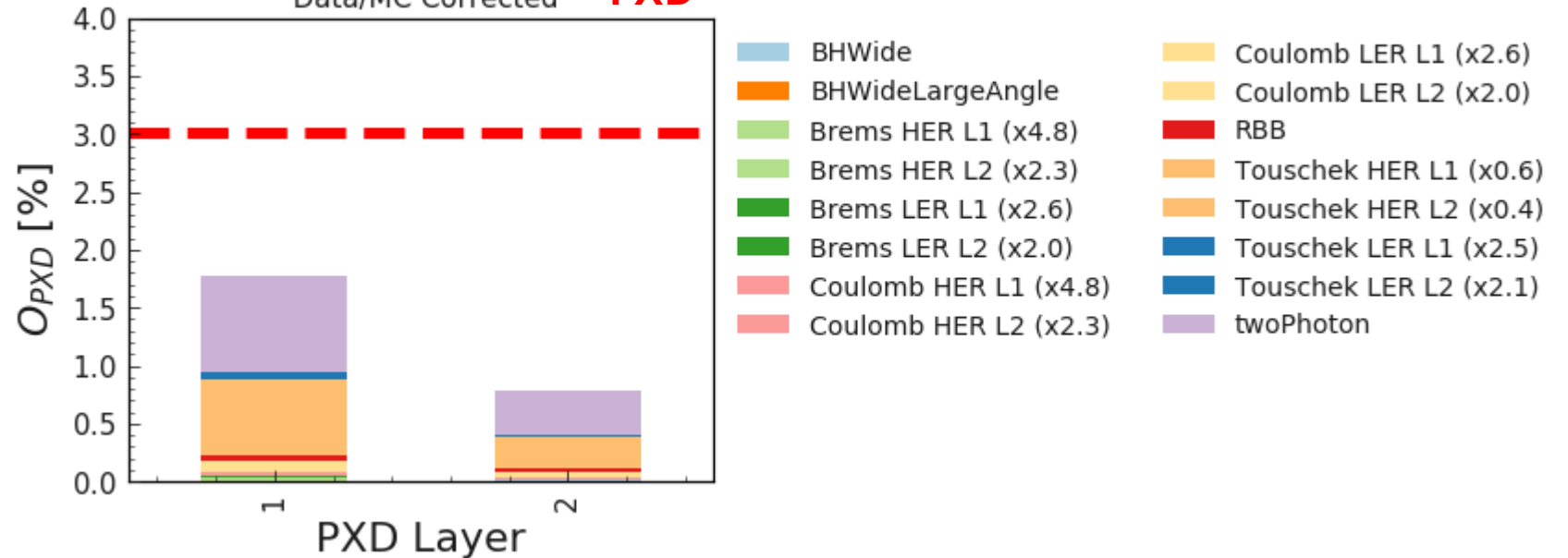
Details on beam-induced background

Extrapolations still under progress

SVD BG estimation @ design luminosity

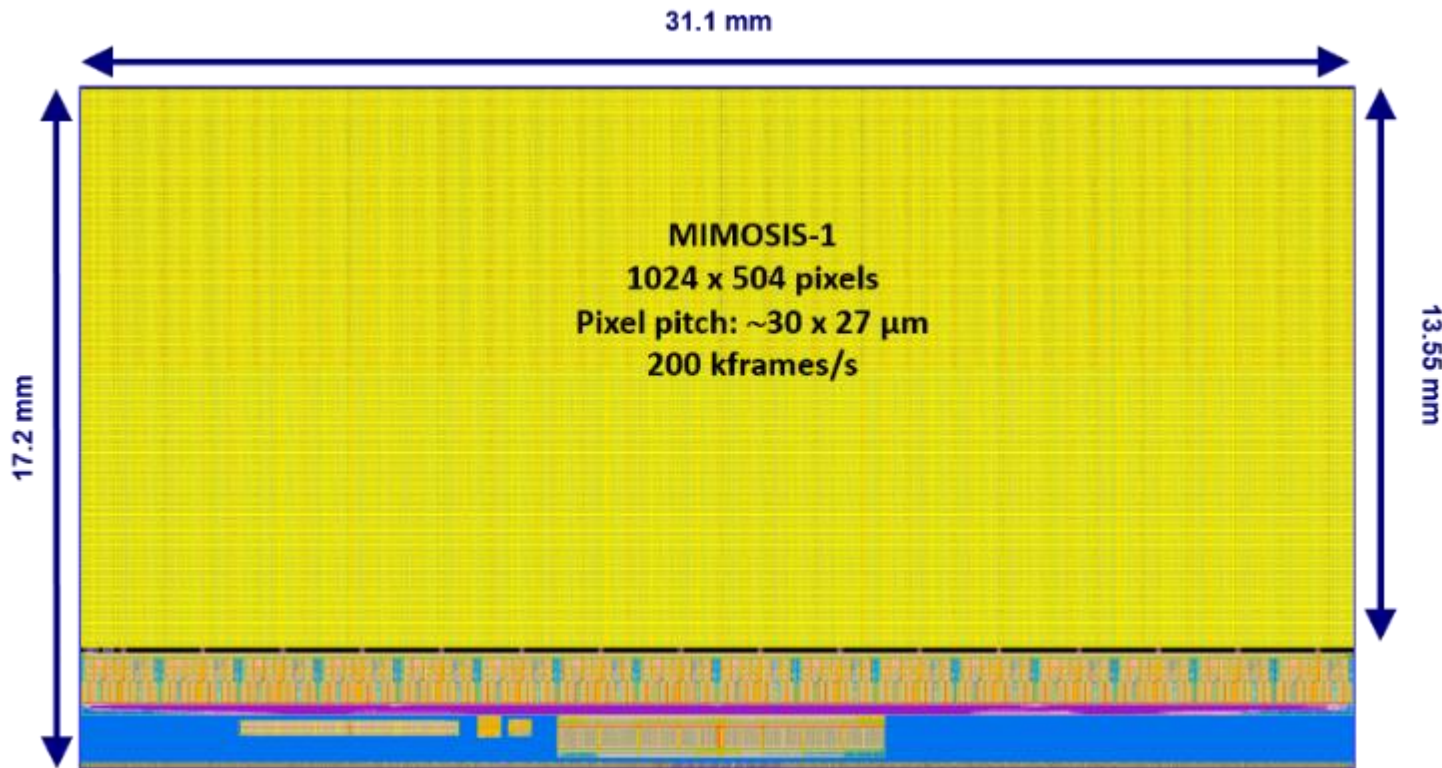


Full Luminosity BG 18:
Data/MC Corrected **PXD**



CMOS pixel sensor

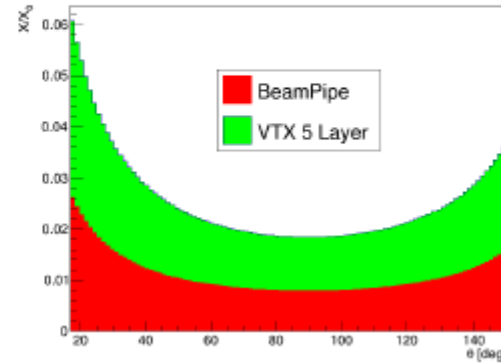
Typical application-ready sensor (180 nm techno)



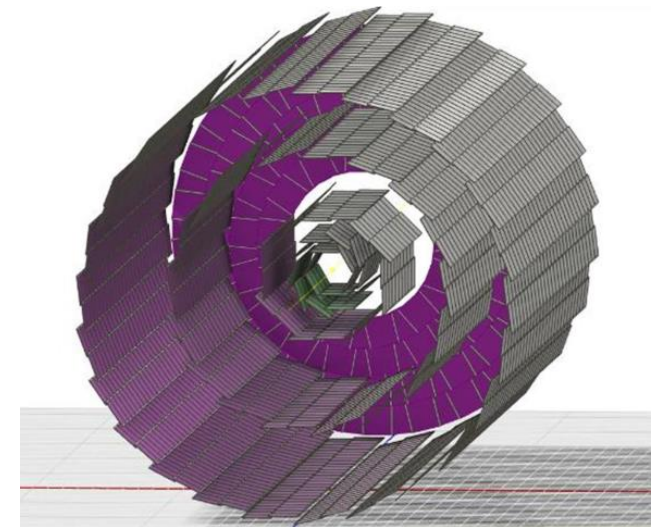
Full pixelated VXD: Geometry details

VTX with 5 pixelated layers

5 layers	1	2	3	4	5
Radius (cm)	1.4	2.2	3.9	8.9	14.0
# ladders	6	10	8	18	26
Sensor type	A	A	A'	A'	A'
# Sensor rows along z direction	1	1	2	4	6

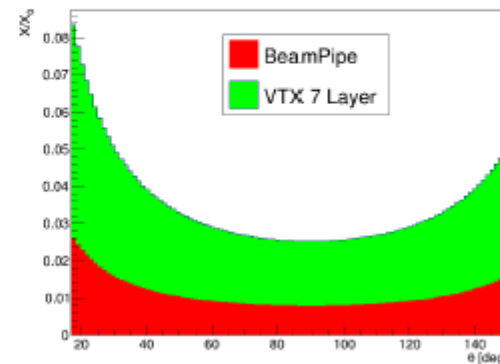


5 layers + 2 disks

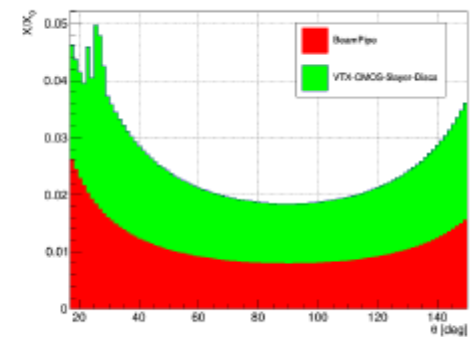
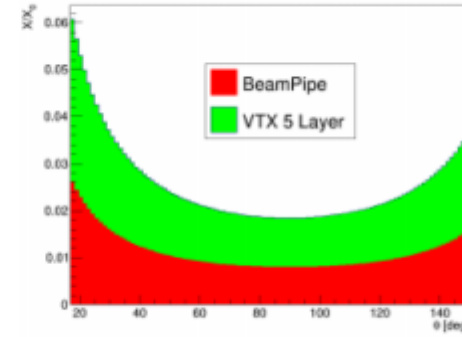
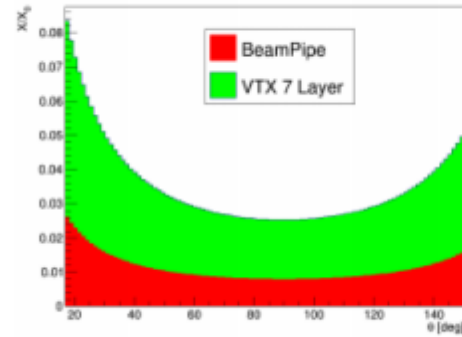
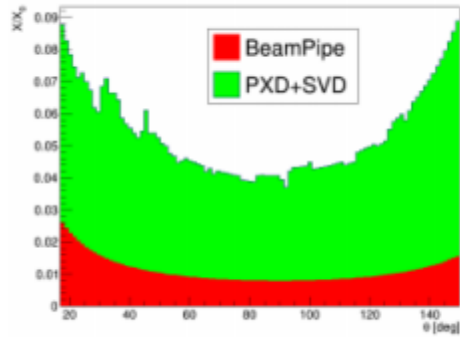


VTX with 7 pixelated layers

7 layers	1	2	3	4	5	6	7
Radius (cm)	1.4	2.2	3.5	6.0	9.0	11.5	13.5
# ladders	6	10	14	12	18	22	26
Sensor type	A	A	A	A'	A'	A'	A'
# Sensor rows along z direction	1	1	2	3	4	5	6



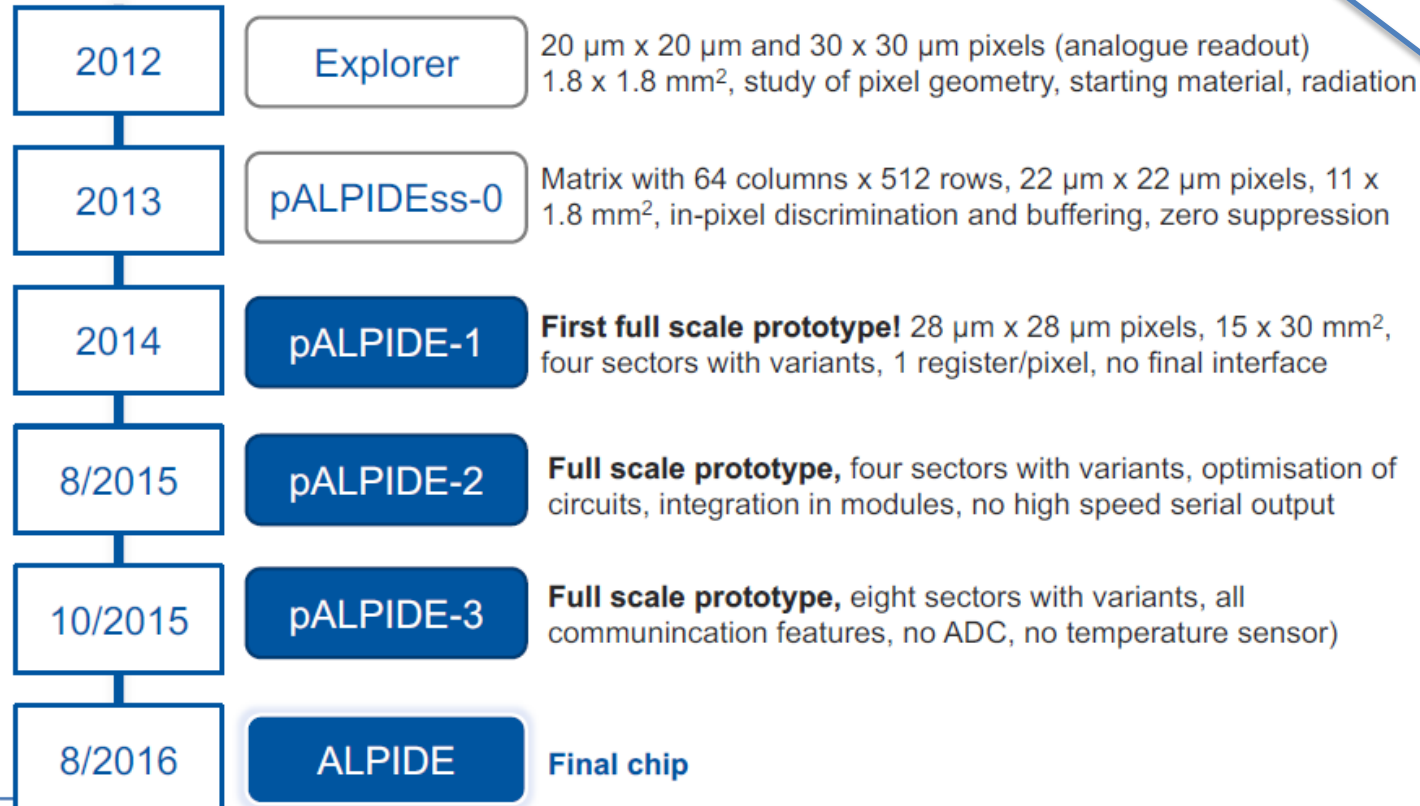
Material budget full pixelated VXD



About timeline: the ALPIDE-ITS case

Chip Development

Design team from CERN, INFN, CCNU, YONSEI, NIKHEF, IRFU, IPHC



~4 years from tech-proto to final sensor

■ Few remarks

- TJ180 nm exploration started in 2011
- This is not a small team

+3 years for assembly
(ALICE-ITS ~10 m²)



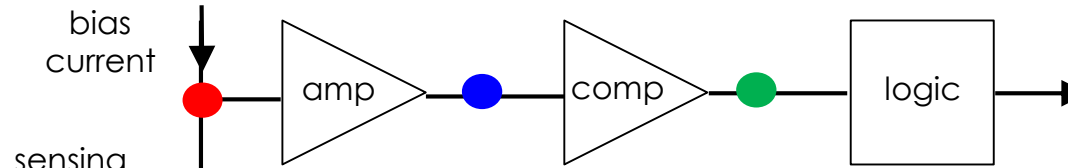
February 22, 2018

P.Riedler CERN, PSI Seminar

Tower Jazz 180 nm time response simulations

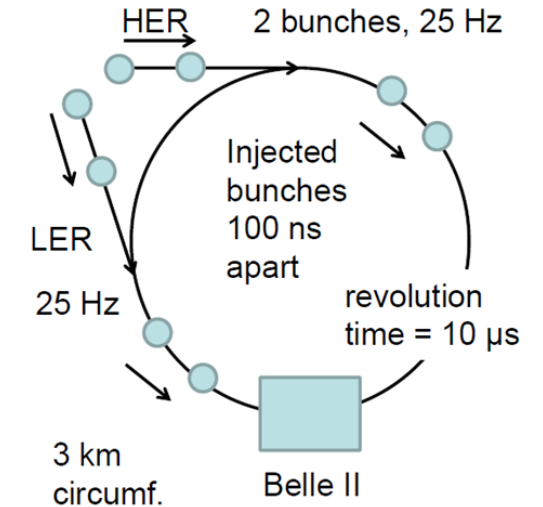
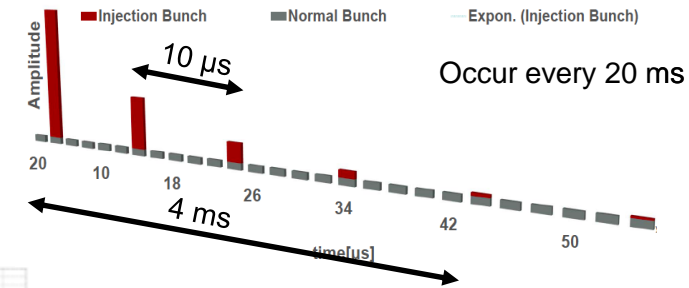
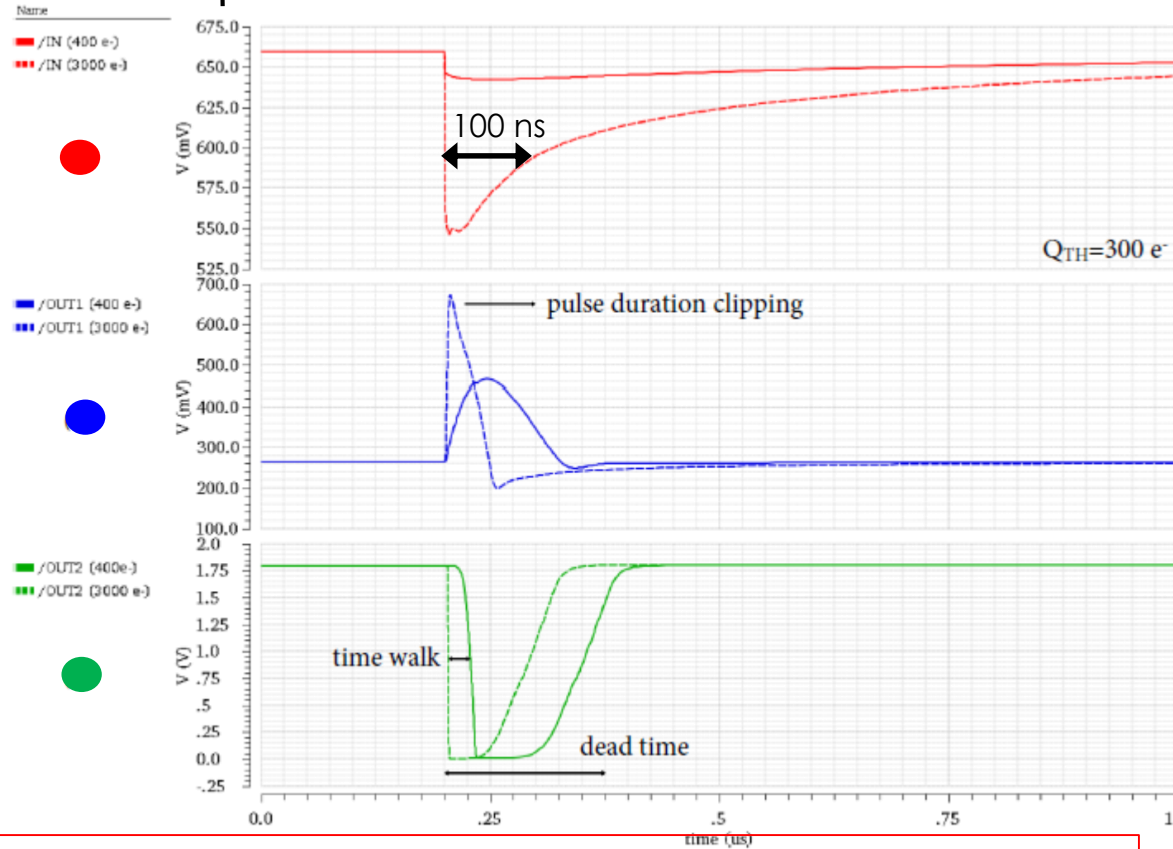


Front-end structure in-pixel



Simulated behavior (MALTA case)

- From I. Berdalovich, JINST 13 (2018) C01023
- Short recovery time for node requires $I_{bias} \sim 500$ nA $\rightarrow 0.9$ μ W/pixel
- ALPIDE with μ s timing reaches 0.040 μ W/pixel



\Rightarrow Suggest gating injection for ~ 100 - 200 ns doable after comparator